# **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# 2PD601A series NPN general purpose transistors; 50 V, 100 mA

Product data sheet Supersedes data of 2002 Jun 26 2004 Feb 12



# NPN general purpose transistors; 50 V, 100 mA

# 2PD601A series

#### **FEATURES**

- Available in SOT323 (SC-70) and SOT346 (SC-59) packages
- Available in three different DC current gain versions (Q, R, S).

# **APPLICATIONS**

• General purpose switching and amplification.

# **DESCRIPTION**

NPN general purpose transistors (see "Simplified outline, symbol and pinning" for package details).

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-	50	V
I <sub>C</sub>	collector current (DC)	_	100	mA
h <sub>FE</sub>	DC current gain			
	group Q	160	260	
	group R	210	340	
	group S	290	460	

### **PRODUCT OVERVIEW**

TVDE NUMBER	PAC	KAGE	MARKING CODE	h CROUD
TYPE NUMBER	PHILIPS	PHILIPS EIAJ		h <sub>FE</sub> GROUP
2PD601AQ	SOT346	SC-59	ZQ	Q
2PD601AR	SOT346	SC-59	ZR	R
2PD601AS	SOT346	SC-59	ZS	S
2PD601AQW	SOT323	SC-70	*6D	Q
2PD601ARW	SOT323	SC-70	*6E	R
2PD601ASW	SOT323	SC-70	*6F	S

# Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
  - \* = W: Made in China.

# SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PINNING		
ITPE NUMBER	SIMPLIFIED OUTLINE AND STMBOL	PIN	DESCRIPTION	
2PD601AQ		1	base	
2PD601AR		2	emitter	
2PD601AS	- 3   3	3	collector	
2PD601AQW				
2PD601ARW	' <b> </b>			
2PD601ASW	<u>1</u>			
	Top view MAM321			

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# **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE					
ITPE NUMBER	NAME	DESCRIPTION	VERSION			
2PD601AQ	_	plastic surface mounted package; 3 leads	SOT346			
2PD601AR						
2PD601AS						
2PD601AQW	_	plastic surface mounted package; 3 leads	SOT323			
2PD601ARW						
2PD601ASW						

# **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	6	V
I <sub>C</sub>	collector current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1			
	SOT346		_	250	mW
	SOT323		_	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Refer to SOT346 (SC-59) and SOT323 (SC-70) standard mounting conditions.

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1		
	SOT346		500	K/W
	SOT323		625	K/W

#### Note

1. Refer to SOT346 (SC-59) and SOT323 (SC-70) standard mounting conditions.

# Soldering

Reflow soldering is the only recommended soldering method.

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# **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 60 V	_	10	nA
		$I_E = 0$ ; $V_{CB} = 60 \text{ V}$ ; $T_j = 150 ^{\circ}\text{C}$	_	5	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 5 V	_	10	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 100 mA; V <sub>CE</sub> = 2 V; note 1	90	_	
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 2 mA; V <sub>CE</sub> = 10 V			
	group Q		160	260	
	group R		210	340	
	group S		290	460	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 100 \text{ mA}; I_B = 10 \text{ mA}; \text{ note 1}$	_	250	mV
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	3	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 2 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	100	_	MHz

# Note

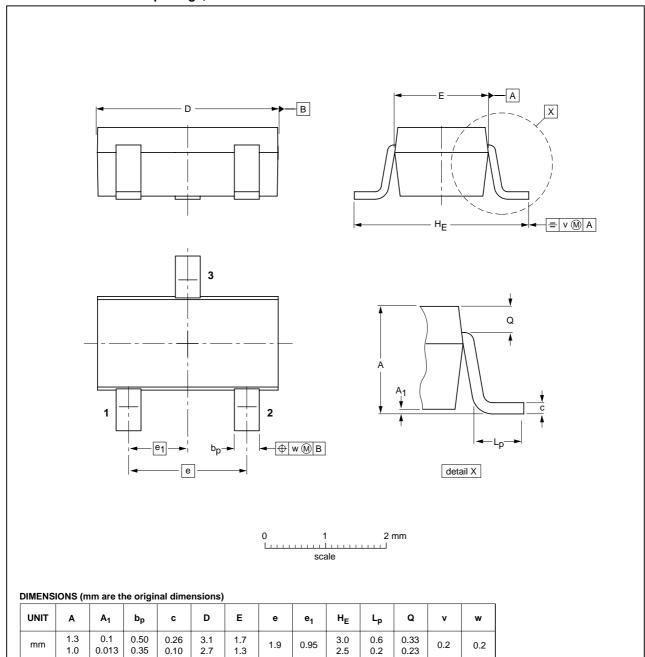
1. Pulse test:  $t_p \leq 300~\mu s;~\delta \leq 0.02.$ 

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# **PACKAGE OUTLINES**

Plastic surface-mounted package; 3 leads SOT346



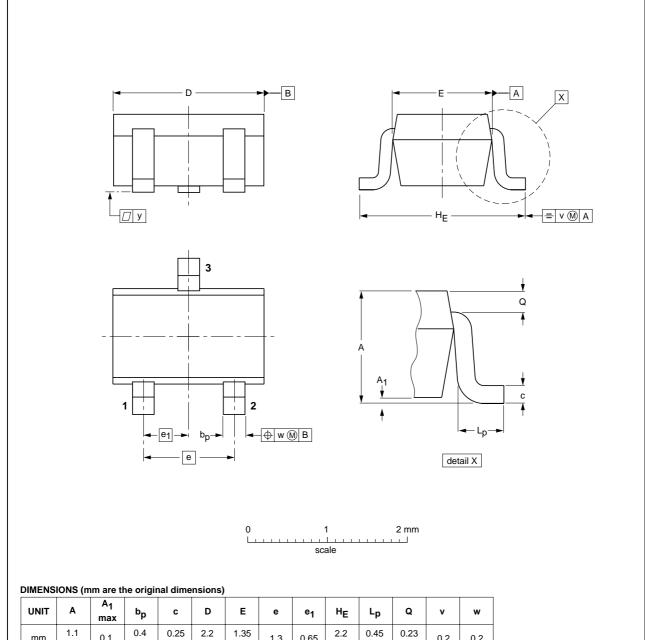
OUTLINE		REFER	EUROPEAN ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT346		TO-236	SC-59A			<del>04-11-11</del> 06-03-16

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# Plastic surface-mounted package; 3 leads

**SOT323** 



UNIT	A	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	V	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT323			SC-70			<del>04-11-04</del> 06-03-16

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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